

SOT789A

leadless surface mounted package; plastic cap; 32 terminations

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	QMAN32
Package type industry code	QMAN32
Package style descriptive code	QMAN (quad microelectronic assembly; no leads)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	16-3-2006

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		11.35	-	11.5	11.65	mm
E	package width		9.35	-	9.5	9.65	mm
A	seated height		1.7	-	1.8	1.9	mm
n ₂	actual quantity of termination		-	-	32	-	



2. Package outline

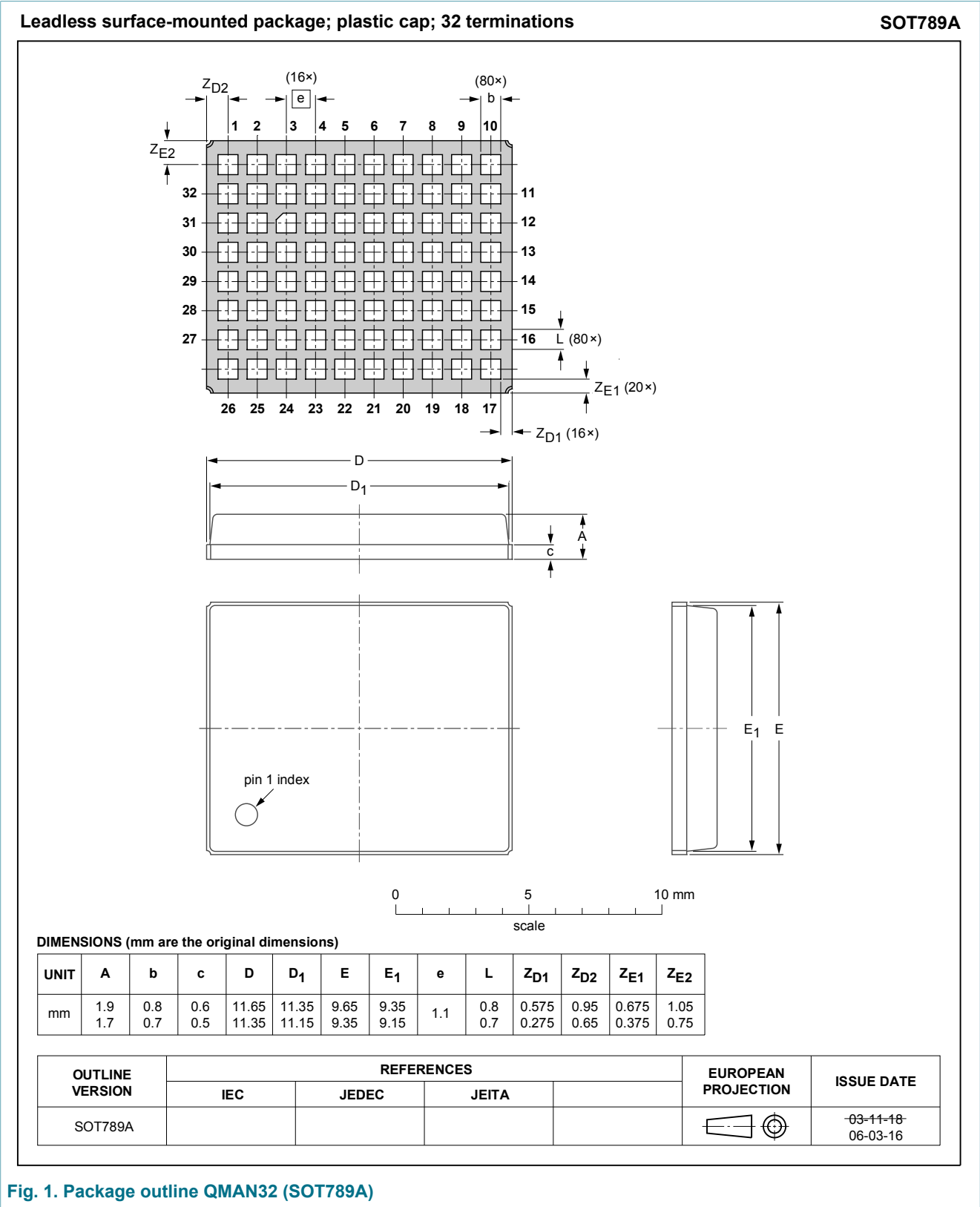


Fig. 1. Package outline QMAN32 (SOT789A)

3. Legal information

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